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# JSKD/JSMD/JSND110

## **Description**

- 1) A package of series of two diodes.
- 2) Heat transfer through alumina ceramic and metal substrate.
- 3) Welding by vacuum welding technology, which provide high reliability.



# **Typical Application**

AC converter, inverter and DC motor.

### Absolute Maximum Ratings (Packaged into modules, unless otherwise specified, TCASE=25°C)

Parameter	Test Conditions	Symbol	Values				11:4
			12	16	18	20	Unit
Operating junction temperature range		Tj	-40~150				$^{\circ}$
Storage temperature range		T <sub>stg</sub>	-40~125				$^{\circ}$
Repetitive peak reverse voltage	Tj=25℃	V <sub>RRM</sub>	1200	1600	1800	2000	V
Non-repetitive peak reverse voltage	Tj=25℃	V <sub>RSM</sub>	1300	1700	1900	2100	V
Average on-state current	Tc=100°C	I <sub>F(AV)</sub>	106				Α
Peak on-state surge current	T <sub>j</sub> =25℃,t <sub>P</sub> =10ms,	IFSM	2968			Α	
I <sup>2</sup> t value for fusing	sin 180°	l <sup>2</sup> t	44000				A <sup>2</sup> s
Insulation voltage	A.C 50Hz(1s/1min)	Viso	3600/3000			V	

## Electrical Characteristics (Packaged into modules, unless otherwise specified, TCASE=25°C)

Parameter	Test Conditions	Symbol	Values	Unit
Peak on-state voltage	I <sub>F</sub> =320A t <sub>P</sub> =380µs	VF	≤1.6	V
Threshold voltage	Tj=150℃	Vто	≤0.85	V
Dynamic resistance	Tj=150℃	Rd	≤1.6	mΩ
	V <sub>R</sub> =V <sub>RRM</sub>			
Repetitive peak reverse current	T <sub>j</sub> =25℃	I <sub>RRM1</sub>	≤100	μA
	T <sub>j</sub> =150℃	I <sub>RRM2</sub>	≤30	mA
Thermal resistance	Junction to case	R <sub>th(j-c)</sub>	0.24	°C/W
	Case to heatsink	R <sub>th(c-s)</sub>	0.12	C/VV



#### **Mechanical Characteristics**

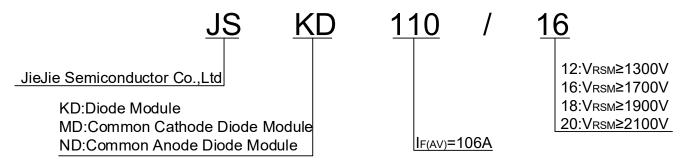
Module size	93mm×21mm		
Module height	30mm		
Terminal distance of (1) /(2) /(3)	20mm		
Mounting torque(M5)	5±15%Nm		
Terminal torque(M5)	3±15%Nm		
69 <sup>+</sup> 0.3 80 <sup>+</sup> 0.5 2-06.4+0.3 22+0.5 A 2-06.4+0.3 22+0.5 80±0.2	(1) (2) (3)  JSKD symbol  (1) (2) (3)  JSMD symbol  (1) (2) (3)  JSND symbol		

#### **Instructions and Precautions**

- 1) There is no severe vibration and shock in operating environment, and there should be no impurity and atmosphere which may corrode metal and damage the insulation in the air-dielectric.
- 2) The operating condition of the product can't out of range of the above parameters.
- 3) When the product is installed on the radiator, the radiator's surface should be confirmed flat, smooth, wipe clean with alcohol, and coated evenly with a layer of thermal grease which thickness is moderate on the contact surface between product and radiator. When the module is fastened on the surface of the radiator, the M5 or M6 screws and spring washers are used and fastened with 5NM torque. After the module is operated 1 hour, all screws must be refastened.
- 4) The connection with the main electrode of module can use copper, welding, socket and so on. The contact surface should be smooth and flat, which make good contact. While the connection with the control electrode of module is installed, attention should be paid to the corresponding connection of each pin. After the completion of the connection, do not plug and pull out the lead of the control electrode freely.



## **Ordering Information**



#### **Performance Curves**

FIG.1: Forward characteristics(per diode)

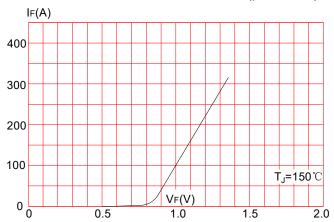


FIG.3: Forward current vs. case temperature

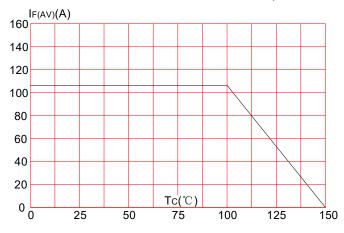


FIG.2: Peak on-state surge current

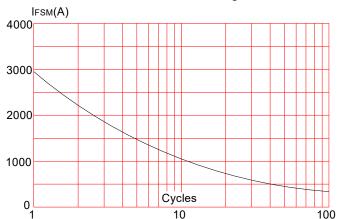
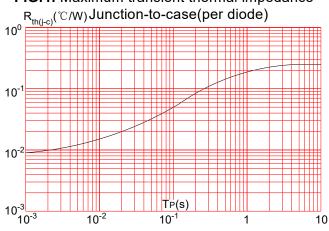


FIG.4: Maximum transient thermal impedance







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